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**April 2015** 

## FGH40N65UFD\_F085 650 V, 40 A Field Stop IGBT

#### **Features**

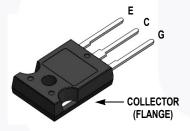
- · High Current Capability
- Low Saturation Voltage:  $V_{CE(sat)}$  = 1.8 V @  $I_C$  = 40 A
- · High Input Impedance
- · Fast Switching
- · RoHS Compliant
- · Qualified to Automotive Requirements of AEC-Q101

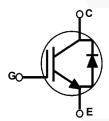
## **Applications**

- · Automotive Chargers, Converters, High Voltage Auxiliaries
- · Inverters, PFC, UPS

### **General Description**

Using novel field stop IGBT technology, Fairchild's field stop IGBTs offer the optimum performance for Automotive Chargers, Inverter, and other applications where low conduction and switching losses are essential.





## **Absolute Maximum Ratings**

Symbol	Description		Ratings	Unit
V <sub>CES</sub>	Collector to Emitter Voltage		650	V
V <sub>GES</sub>	Gate to Emitter Voltage		± 20	V
I <sub>C</sub>	Collector Current	$@T_C = 25^{\circ}C$	80	Α
·C	Collector Current	@ T <sub>C</sub> = 100°C	40	Α
I <sub>CM (1)</sub>	Pulsed Collector Current @ T <sub>C</sub> = 25°C		120	Α
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	290	W
י ט	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	116	W
TJ	Operating Junction Temperature		-55 to +150	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

### **Thermal Characteristics**

Symbol	Parameter	Тур	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	0.43	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	1.45	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	40	°C/W

Notes:
1: Repetitive rating: Pulse width limited by max. junction temperature

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	<b>Packing Method</b>	Reel Size	Tape Width	Quantity
FGH40N65UFDTU_F085	FGH40N65UFD	TO-247	Tube	N/A	N/A	30

## Electrical Characteristics of the IGBT $T_C = 25^{\circ}$ C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 250 μA	650	-	-	V
ΔBV <sub>CES</sub> ΔΤ <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V, } I_{C} = 250 \mu\text{A}$	-	0.6	-	V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0 V$	-	-	250	μА
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	\ <sub>\(\sigma\)</sub> -	±400	nA
On Charac	teristics					
$V_{GE(th)}$	G-E Threshold Voltage	$I_C = 250 \mu A, V_{CE} = V_{GE}$	4.0	5.2	6.5	V
		I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	-	1.8	2.4	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V, T <sub>C</sub> = 125°C	-	2.0	-	V
Dynamic C	haracteristics					
C <sub>ies</sub>	Input Capacitance		-	1860	-	pF
C <sub>oes</sub>	Output Capacitance	V <sub>CE</sub> = 30 V <sub>,</sub> V <sub>GE</sub> = 0 V, f = 1 MHz	-	200	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	- 1 - 1 IVII IZ	-	65	-	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	23	-	ns
t <sub>r</sub>	Rise Time		-	35	- ,/	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A},$	-	126	-	ns
t <sub>f</sub>	Fall Time	$R_G = 10 \Omega$ , $V_{GE} = 15 V$ ,	-	26	60	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C	-	1.28	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.50	- (	mJ
E <sub>ts</sub>	Total Switching Loss		-	1.78	- \	mJ
t <sub>d(on)</sub>	Turn-On Delay Time		-	21	-	ns
t <sub>r</sub>	Rise Time		-	39	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A},$	-	131	-	ns
t <sub>f</sub>	Fall Time	$R_G = 10 \Omega, V_{GE} = 15 V,$	-	72	-	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 125°C	-	1.62	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.79		mJ
E <sub>ts</sub>	Total Switching Loss		-	2.41	-	mJ
Qg	Total Gate Charge		-	119	-	nC
Q <sub>ge</sub>	Gate to Emitter Charge	V <sub>CE</sub> = 400 V, I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	-	14	-	nC
Q <sub>gc</sub>	Gate to Collector Charge	▼GE - 10 ▼	-	64	-	nC

## Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Unit
V Di	V <sub>FM</sub> Diode Forward Voltage	IF = 20 A	T <sub>C</sub> = 25°C	-	1.80	2.6	V
FIVI			T <sub>C</sub> = 125°C	-	1.71	-	
t <sub>rr</sub>	Diode Reverse Recovery Time	$I_F = 20 \text{ A}, \text{ di}_F/\text{dt} = 200 \text{ A}/\mu\text{s}$	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	65	-	ns
ai.	2.000 1.010.00 1.00010.		T <sub>C</sub> = 125°C	-	215	-	
Q <sub>rr</sub>	Diode Reverse Recovery Charge		$T_{\rm C} = 25^{\rm o}{\rm C}$	-	145	-	nC
			$T_{\rm C} = 125^{\rm o}{\rm C}$	-	775	-	

**Figure 1. Typical Output Characteristics** 

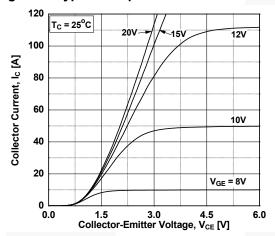


Figure 3. Typical Saturation Voltage Characteristics

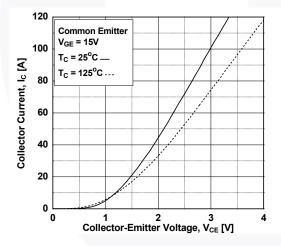


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

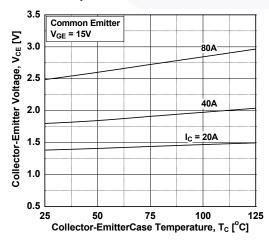


Figure 2. Typical Output Characteristics

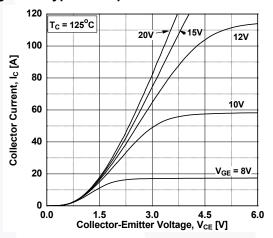


Figure 4. Transfer Characteristics

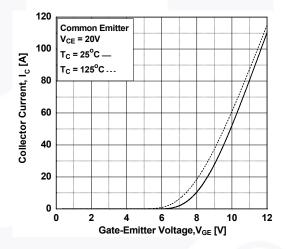


Figure 6. Saturation Voltage vs.  $V_{\text{GE}}$ 

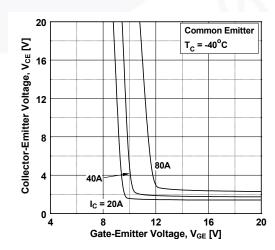


Figure 7. Saturation Voltage vs. V<sub>GE</sub>

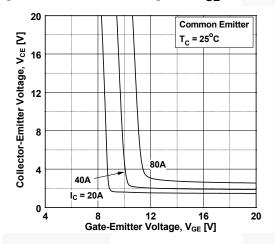


Figure 9. Capacitance Characteristics

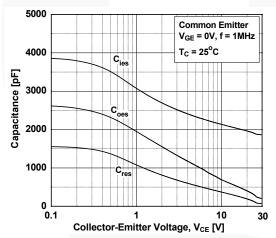


Figure 11. SOA Characteristics

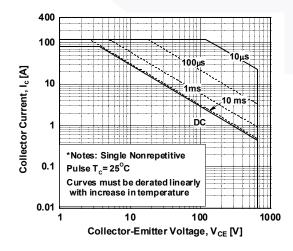


Figure 8. Saturation Voltage vs. V<sub>GE</sub>

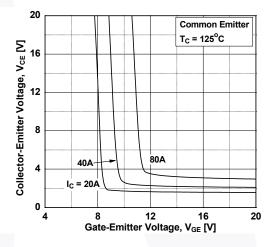


Figure 10. Gate charge Characteristics

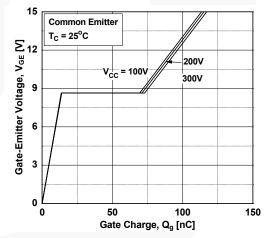


Figure 12. Turn-on Characteristics vs.
Gate Resistance

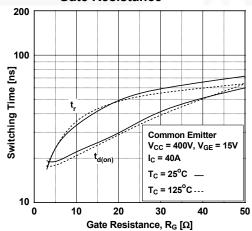


Figure 13. Turn-off Characteristics vs.
Gate Resistance

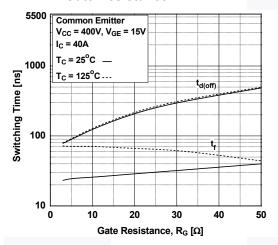


Figure 15. Turn-off Characteristics vs. Collector Current

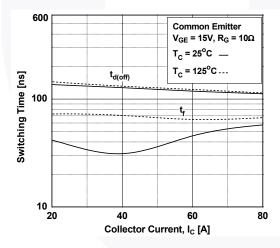


Figure 17. Switching Loss vs. Collector Current

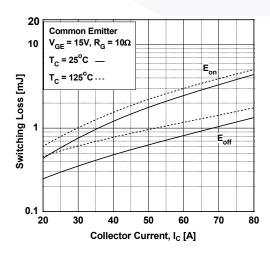


Figure 14. Turn-on Characteristics vs.
Collector Current

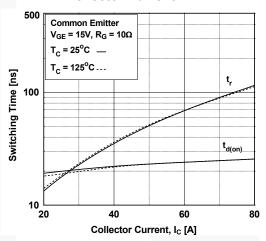


Figure 16. Switching Loss vs. Gate Resistance

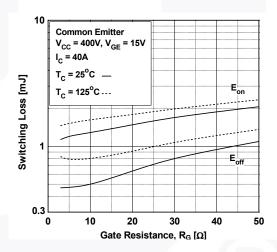


Figure 18. Turn off Switching SOA Characteristics

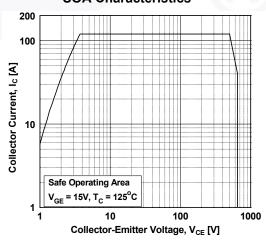


Figure 19. Forward Characteristics

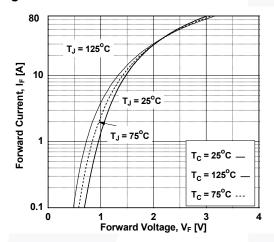


Figure 21. Stored Charge

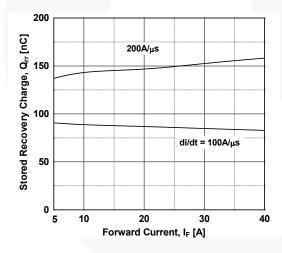


Figure 20. Reverse Current

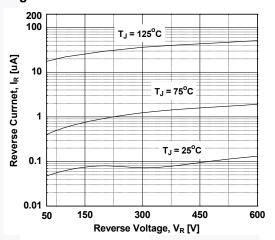


Figure 22. Reverse Recovery Time

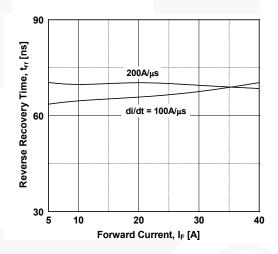
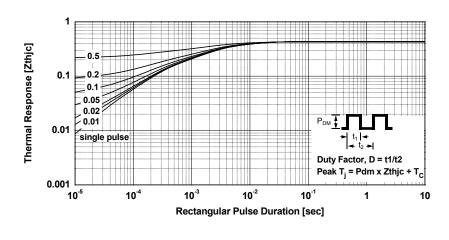
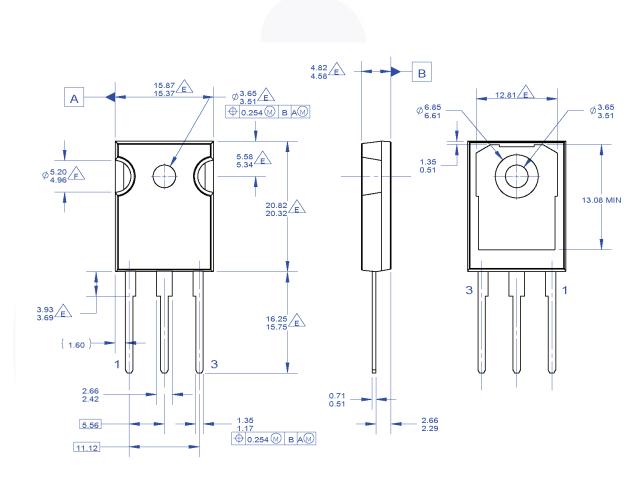


Figure 23. Transient Thermal Impedance of IGBT





NOTES: UNLESS OTHERWISE SPECIFIED.

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- A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH. AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5 1994
- DOES NOT COMPLY JEDEC STANDARD VALUE
- NOTCH MAY BE SQUARE
- G. DRAWING FILENAME: MKT-TO247A03\_REV03

Figure 24. TO-247 3L - TO-247, MOLDED, 3 LEAD, JEDEC VARIATION AB

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